

IN THE ABSTRACT

Please cancel the Abstract of the Disclosure in the application, and add the following replacement Abstract of the Disclosure:

Abstract of the Disclosure

A method of controlling contact load in an apparatus for mounting electronic components on a substrate includes moving a head holding an electronic component down by a predetermined distance. Contact load is measured after moving the head down. A determination is made as to whether the measured contact load has reached the target contact load. The moving and measuring are repeated until the measured contact load reaches the predetermined target contact load.